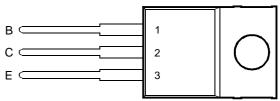
- Designed for Complementary Use with BD646, BD648, BD650 and BD652
- 62.5 W at 25°C Case Temperature
- 8 A Continuous Collector Current
- Minimum h_{FE} of 750 at 3 V, 3 A

TO-220 PACKAGE (TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT	
	BD645		80		
Collector-base voltage (I _E = 0)	BD647	\/	100	V	
	BD649	V _{CBO}	120		
	BD651		140		
	BD645		60	V	
Collector-emitter voltage (I _B = 0)	BD647	V	80		
	BD649	V _{CEO}	100		
	BD651		120		
Emitter-base voltage			5	V	
Continuous collector current			8	Α	
Peak collector current (see Note 1)			12	Α	
Continuous base current			0.3	Α	
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)		P _{tot}	62.5	W	
Continuous device dissipation at (or below) 25°C free air temperature (see Note 3)		P _{tot}	P _{tot} 2		
Unclamped inductive load energy (see Note 4)		½LI _C ²	50	mJ	
Operating junction temperature range		Tj	-65 to +150	°C	
Storage temperature range			-65 to +150	°C	
Lead temperature 3.2 mm from case for 10 seconds			260	°C	

NOTES: 1. This value applies for $t_p \le 0.3$ ms, duty cycle $\le 10\%$.

- 2. Derate linearly to 150°C case temperature at the rate of 0.4 W/°C.
- 3. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.
- 4. This rating is based on the capability of the transistor to operate safely in a circuit of: L = 20 mH, $I_{B(on)}$ = 5 mA, R_{BE} = 100 Ω , $V_{BE(off)}$ = 0, R_S = 0.1 Ω , V_{CC} = 20 V.



BD645, BD647, BD649, BD651 NPN SILICON POWER DARLINGTONS

MAY 1993 - REVISED MARCH 1997

electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER TEST CONDITIONS		MIN	TYP	MAX	UNIT				
V _{(BR)CEO}	Collector-emitter breakdown voltage	I _C = 30 mA	I _B = 0	(see Note 5)	BD645 BD647 BD649 BD651	60 80 100 120			V
I _{CEO}	Collector-emitter cut-off current	$V_{CE} = 30 \text{ V}$ $V_{CE} = 40 \text{ V}$ $V_{CE} = 50 \text{ V}$ $V_{CE} = 60 \text{ V}$	$I_{B} = 0$ $I_{B} = 0$ $I_{B} = 0$ $I_{B} = 0$		BD645 BD647 BD649 BD651			0.5 0.5 0.5 0.5	mA
Ісво	Collector cut-off current	V _{CB} = 50 V	I _E = 0 I _E = 0	$T_{C} = 150^{\circ}C$ $T_{C} = 150^{\circ}C$ $T_{C} = 150^{\circ}C$ $T_{C} = 150^{\circ}C$	BD645 BD647 BD649 BD651 BD645 BD647 BD649 BD651			0.2 0.2 0.2 0.2 2.0 2.0 2.0 2.0	mA
I _{EBO}	Emitter cut-off current	V _{EB} = 5 V	I _C = 0	(see Notes 5 and	l 6)			5	mA
h _{FE}	Forward current transfer ratio	V _{CE} = 3 V	I _C = 3 A	(see Notes 5 and	16)	750			
V _{CE(sat)}	Collector-emitter saturation voltage	$I_B = 12 \text{ mA}$ $I_B = 50 \text{ mA}$	$I_C = 3 A$ $I_C = 5 A$	(see Notes 5 and	16)			2 2.5	V
V _{BE(sat)}	Base-emitter saturation voltage	I _B = 50 mA	I _C = 5 A	(see Notes 5 and	16)			3	V
V _{BE(on)}	Base-emitter voltage	V _{CE} = 3 V	I _C = 3 A	(see Notes 5 and	16)			2.5	V

NOTES: 5. These parameters must be measured using pulse techniques, t_p = 300 μ s, duty cycle \leq 2%.

thermal characteristics

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			2.0	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

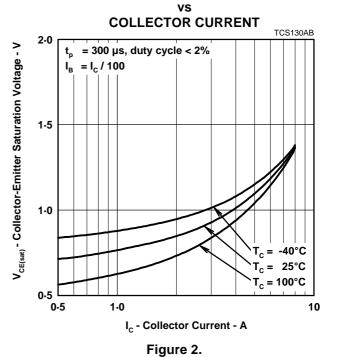
^{6.} These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

TYPICAL CHARACTERISTICS

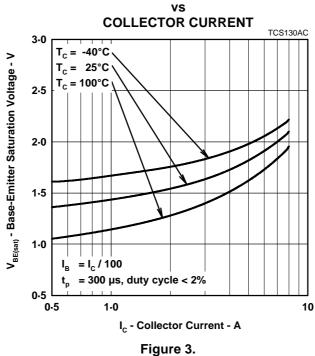
TYPICAL DC CURRENT GAIN VS COLLECTOR CURRENT TCS130AD Tc = -40° C Tc = 25° C Tc = 100° C Tc = 100° C Tc = 3 V Tc = 300 µs, duty cycle < 2% 1000 1_{c} - Collector Current - A

Figure 1.

COLLECTOR-EMITTER SATURATION VOLTAGE

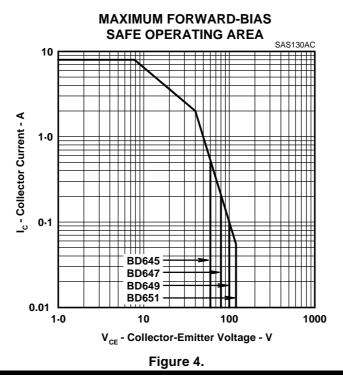


BASE-EMITTER SATURATION VOLTAGE



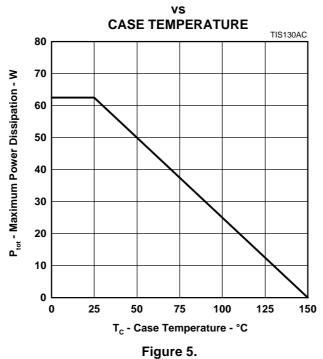


MAXIMUM SAFE OPERATING REGIONS



THERMAL INFORMATION

MAXIMUM POWER DISSIPATION



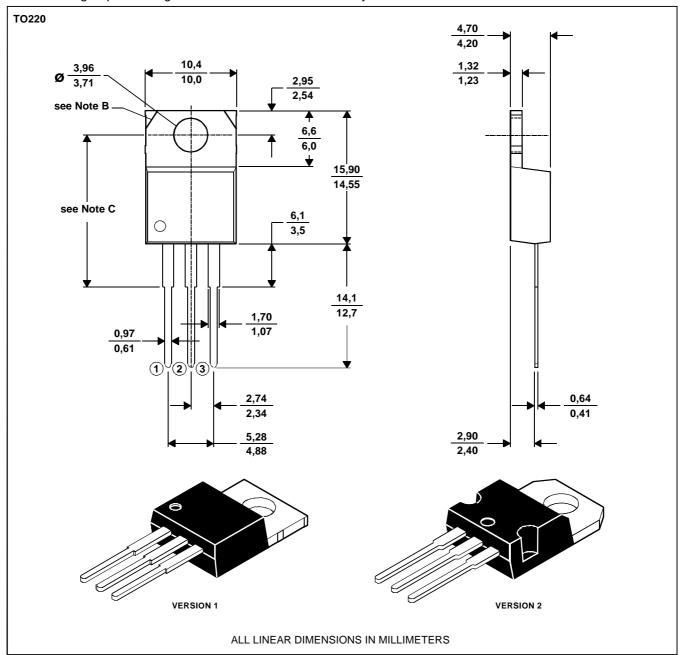
PRODUCT INFORMATION

MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

B. Mounting tab corner profile according to package version.

C. Typical fixing hole centre stand off height according to package version. Version 1, 18.0 mm. Version 2, 17.6 mm. MDXXBE



BD645, BD647, BD649, BD651 NPN SILICON POWER DARLINGTONS

MAY 1993 - REVISED MARCH 1997

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